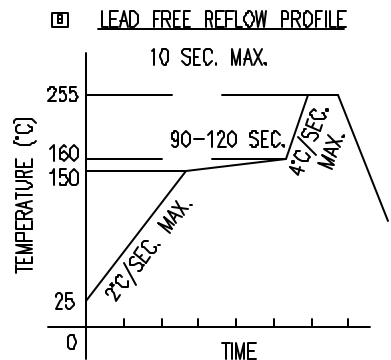
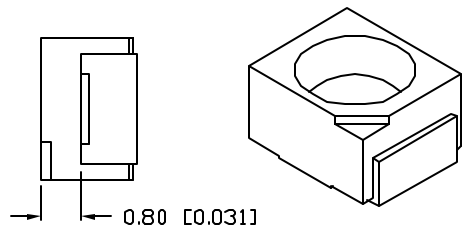
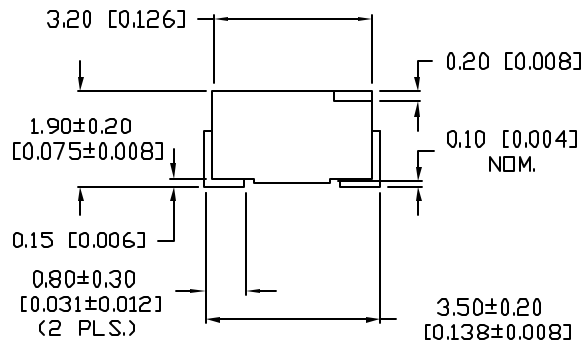
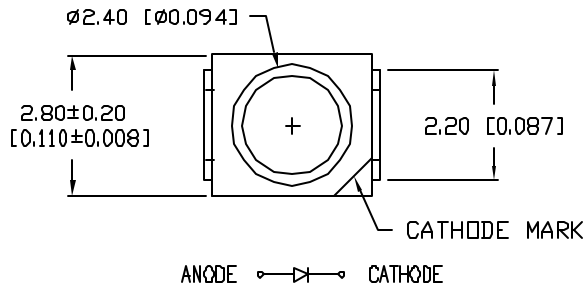
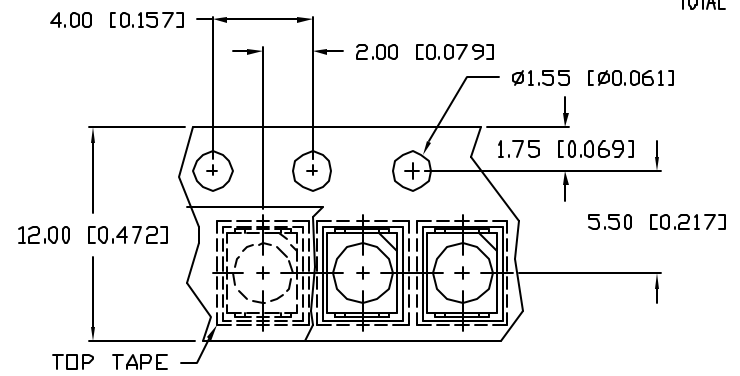
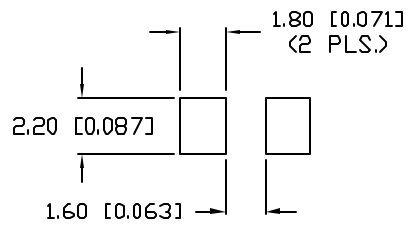


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TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



TAPE FEED DIRECTION

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+DECIMAL PRECISION} -0.00 MAX= ^{+0.00} -DECIMAL PRECISION

PART NUMBER		REV.
SML-LX2832ZIC-TR		B
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11148.	2.8.05

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		630		nm	
FORWARD VOLTAGE		2.4	2.8	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		800		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	120	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



UNCONTROLLED DOCUMENT

REV.	PART NUMBER
B	SML-LX2832ZIC-TR

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2.8mm x 3.2mm SURFACE MOUNT LED WITH REFLECTOR,
630nm TS AlInGaP RED LED, WATER CLEAR LENS,
1,500 PIECES PER TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: GT	CHECKED BY:	APPROVED BY:	DATE: 11.19.01
			PAGE: 1 OF 1
			SCALE: N/A